

Title (en)
METHODS AND APPARATUS FOR INSPECTING A SUBSTRATE FOR DEFECTS AND LOCATING SUCH DEFECTS IN THREE DIMENSIONS USING OPTICAL TECHNIQUES

Title (de)
VERFAHREN UND VORRICHTUNG ZUM UNTERSUCHEN EINES SUBSTRATS AUF DEFEKTE UND ORTUNG DERARTIGER DEFEKTE IN DREI DIMENSIONEN UNTER VERWENDUNG OPTISCHER TECHNIKEN

Title (fr)
PROCÉDÉS ET APPAREIL D'INSPECTION D'UN SUBSTRAT À LA RECHERCHE DE DÉFAUTS ET LOCALISATION DESDITS DÉFAUTS EN TROIS DIMENSIONS À L'AIDE DE TECHNIQUES OPTIQUES

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Application
EP 16732187 A 20160616

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Abstract (en)
[origin: WO2016205456A1] Methods and apparatus for inspecting a substrate for defects and locating such defects in three dimensions include: orienting the substrate such that the substrate has a width dimension in an X-axis, a height dimension in a Y-axis, and a thickness dimension in a Z-axis; directing a first light beam from an angle of +A degrees from a Z-axis of symmetry; directing second light beam from an angle -A degrees from the Z-axis of symmetry; detecting the first and second light beams that have passed through, and have been affected by any defects a first and/or second opposing major surface of the substrate; and computing X, Y, and Z positions of the defects with sufficient precision to ascertain on which of the first and second opposing major surfaces of the substrate each of the defects are disposed.

IPC 8 full level
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Citation (search report)
See references of WO 2016205456A1

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